

STRUCTURE PRODUCT NAME	:	Silicon Monolithic Integrated Circuit DC/DC converter IC for camera module for car navigation system
MODEL NAME	:	B D 8 6 7 6 K N
BLOCK DIAGRAM	• +1.2V • +15V	Fig 2 output synchronous step down DC/DC converter output synchronous step down DC/DC converter output boost DC/DC converter and LDO regulator

- -5.5V output Voltage control charge pump (negative voltage)
- Soft start function
- Reset function
- Building in low voltage and over voltage protection function
- Building in terminal RT OPEN/SHORT protection
- The frequency can be set by external resistance
- Protection control with built-in sequencer
- VQFN-36 package (6.2mm Package)

◎ ABSOLUTE MAXIMUM RATING: (Ta=25°C)

Parameter	Symbol		Limits		Unit
VIN supply voltage	VIN	-0.3	~	+18.0	V
PVIN supply voltage	PVIN	-0.3	~	VIN+0.3	V
V33IN Input terminal voltage	V33IN	-0.3	~	5.0	V
V16 terminal voltage	V16	-0.3	~	+20.0	V
CP terminal voltage	CP	V33IN-0.3	~	+10.0	V
MV66 terminal voltage	MV66	-10.0	~	+0.3	V
Terminal voltage 1*2*3	VINOUT1	-0.3	~	VIN+0.3	V
Terminal voltage 2 ^{*4}	VINOUT2	-0.3	~	V33IN+0.3	V
Terminal voltage 3 ^{*5}	VOUT3	-0.3	~	V16+0.3	V
Terminal voltage 4 ^{*6}	VOUT4	-0.3	~	CP	V
Terminal voltage 5 ^{*7}	VOUT5	MV66-0.3	~	+0.3	V
Power dissipation	Pd		0.875 ^{*1}		W
Operating temperature	Topr	-40	~	+85	°C
Storage temperature	Tstg	-55	~	+150	°C

*1 70mmx70mm, thickness1.6mm, less than 3% share of copper foil when implementing glass epoxy board.

Operating at higher than Ta=25°C, 7.0mW shall be reduced per 1

*2 Input terminal voltage:CTL1(32pin), CTL2(33pin), CTL3(34pin), CTL4(35pin), TEST1(9pin), TEST2(10pin), V33(6pin),V12(14pin)

*3 Output terminal voltage: RT(1pin),RSTO(3pin),RSTDLY(4pin),SS33(5pin),SS12(13pin),SS16(25pin),FC33(7pin),

FC12(15pin),FC16(28pin),TEST3(31pin),SW33(11pin),V33(6pin)

*4 SW12(17pin) terminal voltage *5 SW16(30pin), V15(26pin) terminal voltage *6 CM(20pin) terminal voltage *7 CR(22pin), MV5(24pin) terminal voltage

OPERATION CONDITION (Please set the power-supply voltage in consideration of a power dissipation.)

Parameter	Symbol	MIN	TYP	MAX	Unit
VIN supply voltage	VIN	4.5	6.0	9.0	V
PVIN supply voltage	PVIN	4.5	6.0	9.0	V
V33IN terminal voltage	V33IN	2.7	3.3	3.6	V

This product is not designed for protection against radioactive rays.



◎ ELECTRICAL CHARACTERISTICS

(Unless otherwise noted Ta=25°C. VIN=6.0V.PVIN=6.0V.CTL1.2.3.4=6.0V.GND=0V)

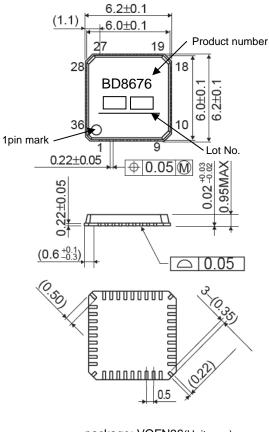
Deven 111	0	spe	ecification	value		0
Parameter	Symbol	MIN	ТҮР	MAX	UNIT	Condition
VIN,PVIN Circuit current 1	I _{Q1}	-	0	50	μA	CTL1,2,3,4=0V
VIN.PVIN Circuit current 2		-		20	m 4	CTL1,2,3,4=VIN、 V33=3.5V
	I _{Q2}	-	-	20	mA	V16=17.0V 、V12=1.4V
Range of DC/DC converter oscillation frequency setting	Fosc	500	1000	1200	kHz	possible to setup at RT terminal.
< 3.3V output Step-down DC/DC converter >						
3.3V output voltage	V ₀₃₃	3.234	3.300	3.366	V	CTL1=VIN
V33 Terminal Discharge resistance	R _{V33DIS}	270	390	500	Ω	
SS33 Terminal Charging current	I _{SS33}	-4.0	-2.5	-1.0	μA	V _{SS33} =1.0V
SS33 Terminal Threshold voltage	V _{SS33TH}	1.0	1.1	1.2	V	V _{SS33} voltage、V _{V33} =3.3V
SS33 Terminal Standby voltage	V _{SS33STB}	0.11	0.15	0.19	V	V _{SS33} voltage (L→H)
SS33 Terminal Protection circuit start voltage	V _{SS33PON}	1.0	1.1	1.2	V	V _{SS33} voltage (L→H)
V33 Terminal Low voltage detection voltage	V _{V33LVP}	1.11	1.32	1.53	V	V _{V33} voltage (H→L)
V33 Terminal Over voltage detection voltage	V _{V33OVP}	4.45	4.95	5.45	V	V _{V33} voltage
< 1.2V output Step-down DC/DC converter >						1
1.2V output voltage	V ₀₁₂	1.176	1.200	1.224	V	CTL1,2=VIN
V12 Terminal Discharge resistance	R _{V12DIS}	270	390	500	Ω	
SS12 Terminal Charging current	I _{SS12}	-4.0	-2.5	-0.1	μA	V _{SS12} =1.0V
SS12 Terminal Threshold voltage	V _{SS12TH}	1.0	1.1	1.2	V	V _{SS12} voltage, V _{V12} =1.2V
SS12 Terminal Standby voltage	V _{SS12STB}	0.11	0.15	0.19	V	V _{SS12} voltage (L→H)
SS12 Terminal Protection circuit start voltage	V _{SS12PON}	1.0	1.1	1.2	V	V_{SS12} voltage (L \rightarrow H)
V12 Terminal Low voltage detection voltage	V _{V12LVP}	0.40	0.48	0.56	V	V _{V12} voltage (H→L)
V12 Terminal Overvoltage detection voltage	V _{V12OVP}	1.62	1.8	0.98	V	V _{V12} voltage
< 16.5V output Boost DC/DC converter >					1	
V16 output voltage	V ₀₁₆	15.65	16.50	17.35	V	CTL1,2,3=VIN
SS16 Terminal Charging current	I _{SS16}	-4.0	-2.5	-1.0	μA	V _{SS16} =1.0V
SS16 Terminal Threshold voltage	V _{SS16TH}	1.0	1.1	1.2	V	V _{SS16} voltage、V _{V15} =15.0V
SS16 Terminal Standby voltage	V _{SS16STB}	0.11	0.15	0.19	V	V _{SS33} voltage (L→H)
SS16 Terminal Protection circuit start voltage	V _{SS16PON}	1.0	1.1	1.2	V	V_{SS16} voltage (L \rightarrow H)
< 15V output LDO >		1		1	r	1
V15 output voltage	V ₀₁₅	14.70	15.00	15.30	V	CTL1,3=VIN
V15 Terminal Discharge resistance	R _{V15DIS}	270	390	500	Ω	
V15 Terminal Overvoltage detection voltage	V _{V150VP}	16.20	18.00	19.80	V	
V15 Terminal Low voltage detection voltage	V _{V15LVP}	5.4	6.0	6.6	V	
< -5.5V output reversing charge pump >				1		1
MV5 output voltage	V _{MV5}	-5.61	-5.50	-5.39	V	CTL1,2,4=VIN
MV5 Terminal Discharge resistance	R _{MV5DIS}	330	470	610	Ω	CTL4=0V
MV5 Terminal Overvoltage detection voltage	V _{MV5OVP}	-8.25	-7.50	-6.75	V	V _{MV5} voltage、V _{V33} =3.3V
MV5 Terminal Protection circuit start voltage	V _{MV5PON}	-4.5	-3.5	-2.5	V	V_{MV5} voltage (H \rightarrow L), V_{V33} =3.3V
MV5 Terminal Low voltage detection voltage	V _{MV5LVP}	-2.5	-2.0	-1.5	V	V_{MV5} voltage (L \rightarrow H), V_{V33} =3.3V
< Reset >						
Reset voltage	V _{RST1}	2.673	2.700	2.727	V	V _{V33} (H→L)
Reset release voltage	V _{RST2}	2.850	3.000	3.150	V	V _{V33} (L→H)
RSTDLY Terminal detection voltage	V _{RSTDLY}	0.800	0.900	1.000	V	V_{RSTDLY} (L \rightarrow H), V_{V33} =3.3V
RSTO Terminal Low output voltage	V _{RSTOL}	-	-	0.5	V	I _{RSTO} =4mA
< Other >						
CTL Terminal input voltage H level voltage	VIHCTL	2.5	-	VIN	V	CTL1,2,3,4
CTL Terminal input voltage L level voltage	VILCTL	-	-	0.5	V	CTL1,2,3,4
CTL Terminal input current	VIFNL		20	35	μA	CTL1,2,3,4=VIN



○PIN ASSIGNMENT

No.	Symbol	Description	No.	Symbol	Description
1	RT	Frequency adjustment resistance connection terminal	19	CP	3.3V and 6.6V switch
2	GND	GND(0V connection)	20	СМ	0V and 6.6V switch
3	RSTO	Reset output	21	PGNDCP	Power GND for Charge pump (0V connection)
4	RSTDLY	Reset release delay element connection terminal	22	CR	0V and -6.6V switch
5	SS33	Soft start adjustment capacity connection terminal for 3.3VDC/DC	23	MV66	-6.6V charge pump output
6	V33	Feedback terminal for 3.3VDC/DC	24	MV5	-5.5V LDO output capacity connection terminal
7	FC33	Error amplifier output terminal for 3.3VDC/DC	25	SS16	Soft start adjustment capacity connection terminal for 16VDC/DC
8	PVIN	Power supply input terminal for 3.3VDC/DC	26	V15	15.0V LDO output
9	TEST1	Test terminal 1(0V connection).	27	V16	Feedback terminal for 16VDC/DC
10	TEST2	Test terminal 2(0V connection).	28	FC16	Error amplifier output terminal for 16VDC/DC
11	SW33	Coil connection terminal for 3.3VDC/DC	29	PGND16	Power GND for 16VDC/DC (0V connection)
12	PGND33	Power GND for 3.3VDC/DC (0V connection)	30	SW16	Coil connection terminal for 16VDC/DC
13	SS12	Soft start adjustment capacity connection terminal for 1.2VDC/DC	31	TEST3	Test terminal 3 (open)
14	V12	Feedback terminal for 1.2VDC/DC	32	CTL1	3.3VDC/DC control terminal
15	FC12	Error amplifier output terminal for 1.2VDC/DC	33	CTL2	1.2VDC/DC control terminal
16	PGND12	Power GND for 1.2VDC/DC (0V connection)	34	CTL3	15.0V LDO control terminal
17	SW12	Coil connection terminal for 1.2VDC/DC	35	CTL4	-5.5V LDO control terminal
18	V33IN	Power supply input terminal for 1.2VDC/DC	36	VIN	Power supply input terminal

◎ PACKAGE OUTLINE



package: VQFN36(Unit:mm) Fig.-1 PACKAGE OUTLINE

◎ BLOCK DIAGRAM

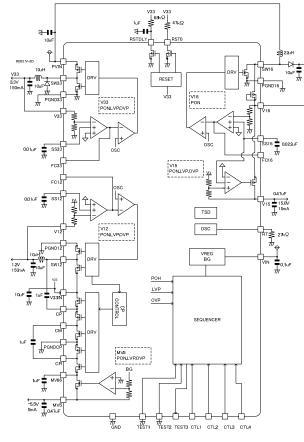


Fig.-2.BLOCK DIAGRAM



ONOTE ON USE

1. About the absolute maximum rating

Attention is brushed off enough to the quality control, it is likely to destroy when the absolute maximum rating such as impressed voltages (VCC_IN,DCIN) and ranges (Topr) of the operating temperature as it is exceeded, the mode of breakings of the short or the opening, etc. cannot be specified, and examine it in this IC to give physical measures for safety such as fuses when a special mode that exceeds the absolute maximum rating is assumed.

2. About the reverse-connection of the power supply connector

IC might destroy it by reversely connecting the power supply connector. Give measures such as putting the diode between power supply terminals of power supply and IC outside for the reverse-touching destruction protection.

3. Power supply line

Please do measures such as putting the bypass capacitor in power supply-GND nearest pin of this IC as the route of the resurrection current to cause the return of the current in which it resurrected it by the counter electromotive force of the coil.

Please confirm the characteristic of the electrolytic capacitor enough as the capacity omission etc. at the low temperature never happen, and decide it. 4. About grand potential

Any state of operation must become the lowest potential about the potential of the terminal GND. Moreover, confirm whether there is terminal that is actually the voltage of GND or less including transients. [Negative power supply terminal CR(22pin) MV66(23pin) MV5(24pin) is excluded.]

5. About the heat design

Think about permissible loss (Pd) in an actual state of use, and do the heat design with the margin enough.

6. About the short and the miss-installation between terminals

Note the direction and the miss-registration of IC enough when you install it in the set substrate. IC might destroy it as well as reversely connecting the power supply connector when installing it by mistake. Moreover, there is fear of destruction when the foreign body enters between terminals, the terminal, the power supply, and grandeur and it is short-circuited.

- 7. About operation in strong electromagnetic field
 - In use in strong electromagnetic field, note that there is a possibility of malfunctioning.
- 8. About the capacitor during output-GND

The current charged the capacitor with when VCC is 0V or is GND and is short-circuited when a big capacitor is connected between GND output by some factors flows into the output and it is likely to destroy it. Give the capacitor between GND output to 0.1µF or less.

9. About the inspection by the set substrate

It is likely to suffer stress to IC and discharge electricity every one process when you connect the capacitor with the pin with low impedance when inspecting it in the set substrate. Moreover, detach it after connecting after the power supply is turned off without fail when detaching it to G in the inspection process, inspecting, and turning off the power supply. In addition, be give the earth to the assembly process as a static electricity measures, and careful enough when it transports and you preserve it.

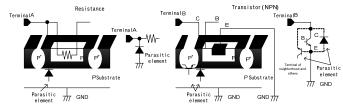
10. About each input terminal

This IC is a monolithic IC which has a P⁺ isolations and P substrate to isolate elements each other.

This P layer and an N layer in each element form a PN junction to construct various parasitic elements.

For instance, the potential difference operates in resistance as shown in the figure below when resistance and the transistor connect it with the terminal and the playground (GND) >(terminal B) joint of PN operates as a parasitic diode in playground (GND) >(terminal A) transistor (NPN). In addition, the NPN transistor of parasitism works with N layer of the element of the above-mentioned parasitic diode and the neighborhood and others in transistor (NPN). A parasitic element in IC composition is inevitably formed because of the potential relation.

A parasitic element can operate, the interference with the circuit operation be caused, it malfunction, and, consequently, it cause destruction. Therefore, do not do the usage that a parasitic element operates as a voltage that is lower than the playground (GND;P substrate) is impressed to the input terminal enough. Moreover, do not impress the voltage to the input terminal when you do not impress the power-supply voltage to IC. Give each input terminal to me the voltage below the power-supply voltage or in the guarantee value of an electric characteristic when you similarly impress the power-supply voltage.



Example of IC of simple structure

11. Earth wiring pattern

If small signal GND and large current GND exist, disperse their pattern. In addition, for voltage change by pattern wiring impedance and large current not to change voltage of small signal GND, each ground terminal of IC must be connected at the one point on the set circuit board. As for GND of external parts, it is similar to the above-mentioned.

12. Thermal Shut-Down

When a thermal shutdown operates, the DC/DC converter controller of all Ch is turned off. When a thermal shutdown is released, the DC/DC converter controller of all Ch becomes an operation beginning from turning off.

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